_,									
	10:37	10:37	10:38	10:38	10:38	10:39	10:39	13:04	13:15
Time Stamp	2004/09/22 10:37	2004/09/22 10:37	2004/09/22 10:38	2004/09/22 10:38	2004/09/22 10:38	2004/09/22 10:39	2004/09/22 10:39	2004/09/22 13:04	2004/09/22 13:15
Time	2004	2004	2004	2004	2004	2004	2004	5004	2004
Plurals	₽ H	0FF	H0	OFF.	OFF	- OFF	OFF.	0FF	H0 .
Default Operator	OR	A.	OR OR	OR	OR	OR	No.	OR	OR
DBs	US-PGPUB; USPAT; EPO; JPO; DERWENT								
Search Query	451/56.ccls.	451/60.ccls.	polish\$3	451/41.ccls. and polish\$3	451/56.ccls. and polish\$3	451/60.ccls. and polish\$3	ped	"3-hydroxy-4-pyrones"	("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sohated adj electrons) (suffurous adj acid)
H.	704	478	254722	2208	480	380	419839	46	955901
Ref #	15	23	SS	S4	SS	98	25	88	83

EAST Search History

S10	955901	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydrogines or	US-PGPUB; USPAT; EPO; JPO; DERWENT	NO.	뇬	2004/09/22 13:17
		hydroxylamine or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)				
S11	303143	("428" or "156" or "51").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF.	2004/09/22 13:18
512	43264	(("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane bornhydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid) ja nd (("428" or "156" or "51").clas.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĸ	440	2004/09/22 13:18
S13	0	"451.clas"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:18
S14	64433	"451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF.	2004/09/22 13:18
515	1097	(("3-hydroxy-4-pyrones") or (hydroxy adj. butyrolactones,) or borane borohydrides (daikylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sokvated adj electronis) (suffurous adj acid)) and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	%	9-FF	2004/09/22 13:19
S16	2868440	reducing agent	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2004/09/22 13:23

2004/09/72 13:23	2004/09/22 13:34	2004/09/22 13:31	2004/09/22 13:31	2004/09/22 13:42
96	P. P		PF6	1 0
NO .	8	80	AR M	К
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane brorbydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (suffurous adj acid) 1 and "451".clas.) and (reducing agent)	(451/41.ccls. and polish\$3) and pad	(451/56.ccls. and polish\$3) and pad	(451/60.ccls. and polish\$3) and pad	(("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj acidn hydrogen hydroquinones) hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sobvated adj electrons) (sulfurous adj acid) and (((451/41.cds. and polish\$3) and pad) or ((451/56.ccs. and polish\$3) and pad) or ((451/60.cds. and polish\$3) and pad))
834	1562	396	263	337
212	518	S19	820	521

EAST Search History

2004/09/22 13:35	2005/01/24 13:20	2004/09/22 13:38
FF 0	F 0	1
&	A C	ъ В
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((('3-hydroxy-4-pyrones") or (hydroxy adi1 butyrolactones) or borane borohydrides (dalkylamine adi boranes) formaldehyde (formic adi acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adi acid) trihydroxybenzene (sobvated adi electrons) (sulfurous adi acid) 1 and (((451/41.cck. and polish\$3) and pad) or ((451/56. cck. and polish\$3) and borane borohydrides (dialkylamine adi borane borohydrides (dialkylamine adi boranes) formaldehyde ((formic adi acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adi acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adi acid) had (((451/41.cck. and polish\$3) and pad) or ((451/60.cck. and polish\$3) and pad) or ((451/61.cck. and polish\$3) and pad))))	((451/41.ccks. and polish\$3) and pad) and ((("3-hydroxy-4-pyrones") or (("3-hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and (((451/41.ccls. and polish\$3) and pad) or ((451/56. ccls. and polish\$3) and pad) or ((451/60.ccls. and polish\$3) and pad) or ((451/60.ccls. and polish\$3) and pad) or	(('3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sohxted adj electrons) (suffurous adj acid) 1 and (((451/56.cds, and polish\$3) and pad)) or ((451/66.cds, and polish\$3) and pad))
64	288	8
825	823	524

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2006/02/14 15:39	2004/09/22 14:22	2004/09/22 14:18	2004/09/22 14:19	2004/09/22 14:22	2004/09/22 14:23	2004/09/22 14:23	2005/01/21 15:29	2005/01/21 15:11
OFF	OFF	9FF	490	OFF	开0	OFF	OFF	OFF.
SO.	OR	OR	K	OR.	SR.	8	ao R	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	USPAT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((73-hydroxy-4-pyrones') or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trilhydroxybenzene (sokvated adj electrons) (suffurous adj acid)) and ((451/41.cds, and polish\$3) and pad)	oxidize\$4 and abrasive and polish\$4	oxidize\$2 and abrasive and polish\$4 and (reducing adj agent) and ((liquid or aqueous) adj carrier)	("4769046" "5489233" \$252742" "595879" "6001269" "601506" "617783" "6126532" "6290736" "6299795" "2002/0010232" "2002/0010232"	tantalum	451/41.ccls.	tantalum and 451/41.ccls.	(\$1-alumina or alpha-alumina or (alpha near alumina)) with abrasive	"451.clas"
288	3038	ı	12	77604	2905	190	895	0
\$225	S26	S27	828	S29	S30	S31	S32	S33

EAST Search History

[<u>s</u>	S34	64929	"451".clas.	US-PGPUB; USPAT; EPO; JPO;	OR	0FF	2005/01/21 15:12
<u> </u>	535	99	S32 and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	0FF	2005/01/21 16:01
<i>σ</i>	S36	6947	(silica or (fumed adj alumina)) with abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:30
vi .	537	1138	(S32 or S36) and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	-H0	2005/01/21 15:30
···	538	11	S3S and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:31
	539	27	537 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	S O S	OFF	2005/01/21 16:01
	S40	1109	S36 and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ОFF	2005/01/21 16:01
	S41	24	S40 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	8	OFF	2005/01/21 16:01
<u> </u>	S42	2	"6454822".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	0FF	2005/01/24 09:38
	S43	64929	"451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	80	- FF	2005/01/24 10:45
<u></u>	S44	195	543 and ((Iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad or abrasive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	NO.	ОFF	2005/01/24 10:48

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4 09:58	4 09:59	4 10:08	4 11:17	4 10:15	:4 10:15	:4 10:15	24 10:15	24 10:16
2005/01/24 09:58	2005/01/24 09:59	2005/01/24 10:08	2005/01/24 11:17	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:16
₩ ₩	0FF	0FF	OFF	0FF	OFF	DFF.		0FF
OR	No.	OR	OR	OR	OR	S.	OR	OR
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT						
543 and ((iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad) or abrasive)	(US-20020182982-\$ or US-20030013387-\$ or US-20040029495-\$ or US-20040132385-\$).did. or (US-6454822-\$ or US-6709316-\$). did.	545 and 546	(silicone adj oxide) with "Si"	silicone near4 metal	silicone near2 metal	silicone near1 metal	S43 and S51	S43 and S50
195	v	2	37	6851	2852	740	-	S
S45	S46	S47	S48	S49	SS0	551	252	S53

EAST Search History

2005/01/24 10:16	2005/01/24 10:17	2005/01/24 10:23	2005/01/24 10:24	2005/01/24 10:47	2005/01/24 10:46	2005/01/24 10:49	2005/01/24 10:49	2005/01/24 10:50	2005/01/24 11:17
- DFF	0FF	1 0	OFF	H0	HO.	0FF	0FF	- FF	0FF
SO S	OR	80	OR	OR	8 8	80	Se .	8 8	8
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT				
S43 and S49	S54 not S51	S54 not S53	S47 and (iridium adj oxide)	S43 and (iridium adj oxide)	"428" clas.	(substrate or wafer or semiconductor or semi-conductor) with (iridium adj oxide)	S43 and (iridium adj oxide)	((substrate or wafer or semiconductor or semi-conductor) with (iridium adj oxide)) and ((polishing adj pad) or abrasive)	(copper adj oxide) with "Cu"
Ħ	10	φ	0	2	212721	609	2	23	1388
S54	\$55	556	252	828	828	098	S61	295	S63

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2/15/06 11:43:50 АМ C:\Documents and Settings\bmuller\by, Documents\EAST\Workspaces\10753138.wsp

665 (rirdium adj oxide) and (polish polishing CMP ("chemical mechanical polishing")) 569 (rirdium adj oxide) and (CMP por US-PGPUB; DR polishing CMP ("chemical mechanical polishing")) 569 (rirdium adj oxide) and (CMP por US-PGPUB; DR polishing CMP ("chemical mechanical polishing")) 569 (rirdium adj oxide) and (CMP por US-PGPUB; DR polishing")) 569 (rirdium adj oxide) and (CMP or US-PGPUB; DR polishing")) 569 (rirdium adj oxide) and (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) and (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) and (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 560 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 561 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing")) 562 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 563 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 564 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 565 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 566 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 570 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 571 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 570 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 571 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 571 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 572 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 573 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 574 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 575 (rirdium adj oxide) same (CMP or US-PGPUB; DR polishing") 576 (rirdium adj oxide) same (CMP or US-PGPUB; DR							
665 (firdium adj oxide) and (polish bolishing CMP ("chemical polishing")) 610, 190; 61	564	8	S63 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT.	OR	- THO	2005/01/24 11:17
44 S65 and (reducing adj agent) USPAT; EPO; JPO; DERWENT 569 (fridium adj oxide) and (CMP (*Chemical mechanical polishing")) USPAT; EPO; JPO; DERWENT 46 (fridium adj oxide) and (CMP or US-PGPUB; (*Chemical mechanical polishing")) USPAT; EPO; JPO; DERWENT 2 "4717581".pn. US-PGPUB; US-PGPUB; OR US-PG	292	999	(rirdium adj oxide) and (polish polishing CMP ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	0FF	2005/01/24 13:23
S69 (firidium adj oxide) and (CMP US-PGPUB; OR C-chemical mechanical polishing") USPAT; EPO; JPO; DERWENT	995	4	S65 and (reducing adj agent)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	- HO	2005/01/24 13:23
("Cthemical mechanical polishing")) ("Cthemical mechanical polishing") ("Cthemical mechanic	295	695	(ridium adj oxide) and (CMP ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR.	00	2005/01/24 13:24
46 (itidium adj oxide) same (CMP or US-PGPUB; OR Crehemical mechanical polishing")) USPAT; PRO; JPO; DERWENT 2 "4717581".pn. US-PGPUB; OR US-PGPUB;	268	995	(ridium adj oxide) and (CMP or ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 13:24
2 "4717581".pn. US-PGPUB; OR USRAT; EPO; JPO; DERWERT USPAT; EPO; JPO; DERWERT	698	94	(tridium adj oxide) same (CMP or ("chemical mechanical polishing"))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	0FF	2005/01/24 14:09
2 "4679572".pn. US-PGPUB; OR USPAT; EPO; JPO; DERWENT CAS. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT S50 451/56.ccls. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT CAS. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT	S70	2	"4717581".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/24 14:09
2567 451/41.ccks. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT; 550 451/56.ccts. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT 427 451/60.ccks. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT EPO; JPO; DERWENT	178	2	"4679572".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	J. J.	2005/01/24 14:11
550 451/56.ccls. and polish\$3 US-PGPUB; OR USPAT; EPO, JPO; DERWENT 427 451/60.cds. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT DERWENT	272	2567	451/41.ccks. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/07/12 10:33
451/60.ccks. and polish\$3 US-PGPUB; OR USPAT; EPO; JPO; DERWENT	S73	250	451/56.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	og.	0FF	2005/07/12 10:33
	S74	427	451/60.ccks. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	0FF	2005/07/12 10:33

EAST Search History

57.5	08	(S72 S73 S74) and ("nH" near2	HS-PGPUR-	ã	OFF	2005/07/12 10:43
	3	(buffering buffer buffer\$4))	USPAT; USOCR; EPO; JPO; DERWENT	5	;	
576	566	(S72 S73 S74) and (surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	0FF	2005/07/12 10:55
277	1183	(ammonium adj hydroxide) same ("pH" near2 (buffering buffer buffer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	0FF	2005/07/12 10:43
878	366	(ammonium adj hydroxide) with ("pH" near2 (buffering buffer buffer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	0FF	2005/07/12 10:44
S79	105	(ammonium adj hydroxide) near4 ("pH" near2 (buffering buffer buffer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	0FF	2005/07/12 10:44
085	2	(S72 S73 S74) and ((advantages advantageous advantag\$5) with surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	0FF	2005/07/12 10:56
581	v	("451".clas.) and ((advantages advantageous advantag\$5) with surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	世0	2005/07/12 11:00
285	9	("451".clas.) and ((desired improve improved improved with surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/07/12 11:05
583	2	"5783489".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/07/12 11:05

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62	4	35.
2006/02/14 16:29	2006/02/14 15:44	2006/02/14 15:45
H0	F-0	0FF
%	OR.	, , , , , , , , , , , , , , , , , , ,
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(polishing adj (pad pads)) and (CMP or "chemical mechanical polishing" or "chemical mechanical palararization") and ((reducing adj agent) with (hydroxylamine and ("3-hydroxy-4-pyrones") or hydroxy adj 1 butyrolactones) or borane or borohydrides or dialkylamine adj borane\$\$\frac{1}{2}\$ or formaldehyde or (formic adj acid) or hydrogen or hydroquimone\$\$\frac{3}{2}\$ or hydrogen or hydroquimone\$\$\frac{3}{2}\$ or hydrogen or kydroquimone\$\$\frac{3}{2}\$ or hydroquimone\$\$\frac{3}{2}\$ or hydrogen or kydroquimone\$\$\frac{3}{2}\$ or hydroquimone\$\$\frac{3}{2}\$ or hydrogen or kydroquimone\$\$\frac{3}{2}\$ or hydrogen or kydroquimone\$\$\frac{3}{2}\$ or hydroquimone\$\$\frac{3}{2}\$ or hydrogen or kydroquimone\$\$\frac{3}{2}\$ or hydroquimone\$\$\frac{3}{2}\$ or hydroquimo	(polishing adj (pad pads)) and (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adj agent) with (fhydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj! butyrolactones) or oborare or borohydrides or (dialkylamine adj boranes3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or hydrogen or kydroquinone\$3 or hydroxybenzene or (solvated adj electrons) or (suffurous adj acid))	((reducing adj agent) with (hydroxylamine with ("C3-hydroxy-4-pyrones") or (hydroxy adj butyrolactones) or borane or borohydrides or (alakylamine adj borane\$\frac{3}{3}\) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$\frac{3}{3}\) or hydrogen or hydroquinone\$\frac{3}{3}\) or hydrogen or hydroquinone\$\frac{3}{3}\) or hydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))
m	m	241
284	285	985

EAST Search History

2006/02/14 15:45	2006/02/14 16:56	2006/02/14 15:49
0FF	F 0	F.
%	K	Ř
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(polishing adj (pad pads)) and ((reducing adj agent) with (hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (dalkylamine adj boranes\$3) or formaldebyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or hydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adjagent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or (hydroxy adj1 butyrolactones) or horane or borothydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adjacid) or hydrogen or hydroquinone\$3 or (hypophosphorous adjacid) or hydrogen or hydroquinone\$3 or (thypophosphorous adjacid) or trihydroxybenzene or (solvated adjectrons) or (sulfurous adjacid)))	(semiconductor wafer polish planarize substrate copper) and (reducing adj agent) with (hydroxylamine and ("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dalkylamine adj boranes3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$5 or (hypophosphorous adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj
m	N	185
285	888	888

2006/02/14 15:49	2006/02/14 15:49	2006/02/14 15:49	2006/02/14 15:56
2006/02	2006/02	2006/0.	2006/0
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A A	ő	OR .	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(wafer polish planarize substrate copper) and ((reducting adj agent) with (hydroxy-lamine and (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or kydroquinone\$\frac{1}{2}\$ or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))	(semiconductor polish planarize substrate copper) and ((reducing adj agent) with (hydroxyalmine and (("3-hydroxy4-pyrones") or (hydroxy adj) butyrolactones) or (hydroxy adj) butyrolactones) or (diakylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (suffurous adj acid)))	(semiconductor planarize substrate copper) and ((reducing ad agent) with (hydroxylamine and (("3-hydroxy-4-pyronas") or (hydroxy adj 1 butyrolactones) or (hidroxy adj 1 butyrolactones) or (dalkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or highoxybenzene or (solvated adj electrons) or (sulfurous adj acid)))	S93 (semiconductor substrate copper) US-PGPUB; OR and ((reducing adj agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or ("("3-hydroxy-4-pyrones") or borane or borohydrides or (dialkylamine adj borane3) or formaledyde or (formic adj acid) or hydrogen or hydroquinone3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))
176	185	185	182
068	591	292	893

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946	H H	开 0	F.
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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(semiconductor copper) and ((reducing adj agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))	(semiconductor substrate) and ((reducing adj agent) with ((reducing adj agent) with (fivdroxylamine and ((?3-hydroxy-4-pyrones*) or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$33 or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))	(semiconductor semiconductors) and ((reducing adj agent) with (hydroxylamine and (("3-hydroxylamine and ("3-hydroxylamine and borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or rihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	("451".clas.) or ("428".clas.) or ("51".clas.)) and ((reducing adjagent) with (hydroxylamine and ("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or thydroxy adj 1 butyrolactones) or or (hydroxy adj 1 butyrolactones) or formale adjacid) or hydrogen or hydroquinone\$3 or (hypophosphorous adjacid) or hydrogen or hydroquinone\$3 or (hypophosphorous adjacid) or (hydroxybenzene or (sokvated adjacid)))
153	104	53	=
894 845	S 6 S	965	265

6:51	16:46	16:51
2/14 1	2/14	12/14
2006/02/14 16:51	2006/02/14 16:46	2006/02/14 16:51
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OR	OR	OR
PO;	PUB;	PUB; ',' ENT ENT
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((polishing adj (pad pads)) or (CMP or "chemical mechanical planarization") and ((reducing adj agent) with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (dalkylamine adj porane\$) or formaldehyde or (formic adj acid) or hydrogen or hydroquimone\$\$\frac{1}{3}\$ or formycophorous adj acid) or hydrogen or hydroquimone\$\$\frac{1}{3}\$ or fyrpophosphorous adj acid) or trihydroxybenzene or (sobwatea adj electrons) or (sulfurous adj acid)))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical methanical palmarization")) and (slurry composition solution) and (slurry composition solution) and ((reducing adj agent) with (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or horane or borohydrides or challehyde or (formic adj acid) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones3 or fhygophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical palanarization")) and (slurry composition) and (slurry composition) and (treducing adj agent) with ("3-hydroxy-4-pyrones") or (hydroxy adj buryrolactones) or horane or borohydrides or chorane or borohydrides or (dalkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or flypophosphorous adj acid) or trihydroxybenzene or (sokvated adj electrons)
345	308	223
865	665	\$10 0

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2006/02/14 16:51	2006/02/14 16:57	2006/02/14 17:17
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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((polishing adi (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical planarization")) and ((reducing adi agent) with (("3-hydroxy-4-pyrones") or (hydroxy adi butyrolactones) or borane or borohydrides or (falkylamine adi borane\$\$\frac{1}{2}\$\text{ormaldehyde or (formic adi acid)} \text{ormaldehyde or (formic adi acid)} \text{or hydroquinone\$\$\frac{1}{2}\$\text{ormaldehyde or (solvated adi electrons)} \text{or (solvated adi electrons)} \text{or (sulfurous adi acid)}))	(CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical phanarization") and ((reducing adjagent) with ((hydroxylamine adjiodieh)) with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or borane or borohydrides or formaldehyde or (formic adjaci) or hydrogen or hydroquinone\$3 or (hypophosphorous adjacid) or hydrogen or hydroquinone\$3 or (hypophosphorous adjacid) or hydroxybenzene or (solvated adjacid)))	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (freducing adjagent) with (pydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or (hydroxy adj1 butyrolactones) or (dalkylamine adj boranes") or formaldehyde or (formic adjacid) or hydrogen or hydroquinone\$3 or frihydroxybenrosne or (sohvated adjaelctrons) or (suffurous adjaelch)))
214	4	4
1 1	\$10 2	33

Page 15

2006/02/14 16:57	2006/02/14 17:01	2006/02/14 17:01
2006/02	2006/0:	2006/0:
F10	940	949
δ.	N N	%
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adjagent) with ((glucose sulfothionate (potassium adjiodide)) with (("3-hydroxy-4-pyrones") or (hydroxy adj butyrolactones) or borane or borohydrides or (flydroxy adj butyrolactones) or formaldehyde or (formic adjacid) or hydrogen or hydroquimone\$\frac{1}{3}\$ or formaldehyde or (formic adjacid) or hydrogen or hydroquimone\$\frac{1}{3}\$ or frihydroxybenzene or (solvated adjelectrons) or (sulfurous adj	((polishing adj (pad pads)) or planarize planarization slurry) and ((reducing adj agent) with ((glucose sulfothionate (potassium adj iodide)) with (("3-hydroxy-4-pyrones") or (hydroxy adj! butyrolactones) or (hydroxy adj! butyrolactones) or oborane or borohydrides or (dalkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or fithydroxybenzene or (solvated adj electron\$) or (sulfurous adj acid) acid))))	((polishing adj (pad pads)) or planarize planarization) and ((reducing adj agent) with ((glucose sulfothionate (potassium adj iodide)) with (("3-hydroxy-4-pyrones") or (hydroxy adj i butyrolactones) or (borane or borohydrides or (dalkylamine adj borane\$\$3\$) or hydrogen or hydroquinone\$\$3\$ or hydrogen or hydroquinone\$\$3\$ or hydrogen or hydroquinone\$\$3\$ or hydrogen or hydroquinone\$\$3\$ or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid) or acid))))
0	4	0
810	\$10 5	\$10 6

105	(CMP or "chemical mechanical	US-PGPUB;	OR.	PFI	2006/02/14 17:49
	polishing" or "chemical mechanical planarization") and halanarization") and halanarization and (hydroxyamine with (("3-hydroxy-4-pyrones") or (hydroxy adj.1 butyrolactones) or horane or broorlydrides or (dialkytamine adj borane\$\frac{1}{2}\) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$\frac{1}{2}\) or fytpophosphorous adj acid) or trihydroxybenzene or (sohvated adj electrons) or (sulfurous adj acid)))	USPAT, EPO; JPO; DERWENT			
105	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and hand (Ndroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid) not (hydrogen adj peroxide)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	O N	H0	2006/02/14 17:48
8	(CMP or "chemical mechanical polishing" or "chemical mechanical phanarization") and hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or (hydrogen adj peroxide) or (hydrogen adj acid) or (hydrogens adj acid) or (hydrogens adj acid) or (thydpophosphorous adj acid) or trihydroxybenzene or (sokvated adj electrons) or (sulfurous adj acid)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	O.	H-0	2006/02/14 17:53
24	S107 not S109	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/02/14 17:49

2006/02/14 17:53	2006/02/15 08:55	2006/02/15 09:20	2006/02/15 09:28	2006/02/15 09:28
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OR	OR	OR	OR	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and planarization" and (hydroxyamine with (("3-hydroxy-4-pyrones") or (hydroxyamile butyrolactones) or borane or borohydrides or (dialkyfamine adj borane\$\$\frac{1}{2}\$\text{ormaldehyde or (formic adj acid)} \text{or hydroquinone\$}\frac{1}{2}\$\text{ormaldehyde or (formic adj acid)} \text{or hydroquinone\$}\frac{1}{2}\$\text{ormaldehyde or (sormaldehyde or (sormaldehyde or (sormaldehyde or (sormaldehyde or thydroquinone\$\$\text{ormaldehyde or (sormaldehyde or (sorbated adj electrons) or (sulfurous adj acid))}	(complexing adj agent) with (chelating adj agent)	10/753138.app.	("20020039839" "20020090820" " 20020102923" "20020111027" "2 0030013387 "20030119319" "59 89233" "5527423" "5691219" "52 58794""[6117783" "61 74063" "6113039" "631803" "64 19554" "6527622").PN.	09/755717.app.
31	339	П	32	
1 2 1	511	S11 3	511	5